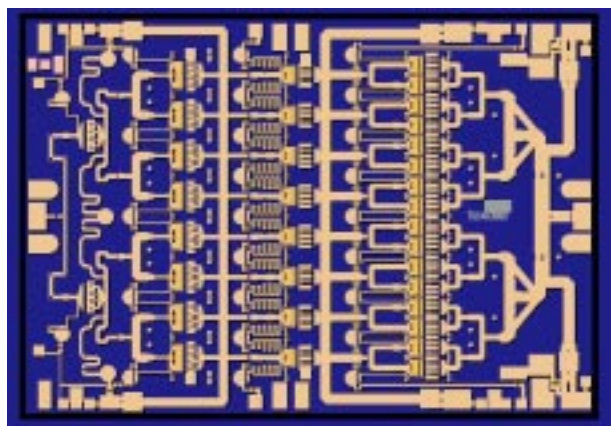


4 Watt Ka Band HPA

TGA4505-EPU



Product Description

The TriQuint TGA4505-EPU is a compact 4 Watt High Power Amplifier MMIC for Ka-band applications. The part is designed using TriQuint's proven standard 0.25 μ m gate Power pHEMT production process.

The TGA4505 provides a nominal 35.5 dBm of output power at 1 dB gain compression from 24-32 GHz with a small signal gain of 23 dB.

The part is ideally suited for low cost emerging markets such as base station transmitters for satellite ground terminals and point to point radio.

The TGA4505-EPU is 100% DC and RF tested on-wafer to ensure performance compliance.

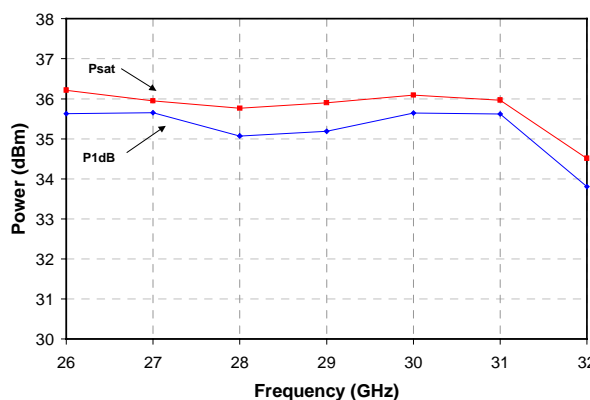
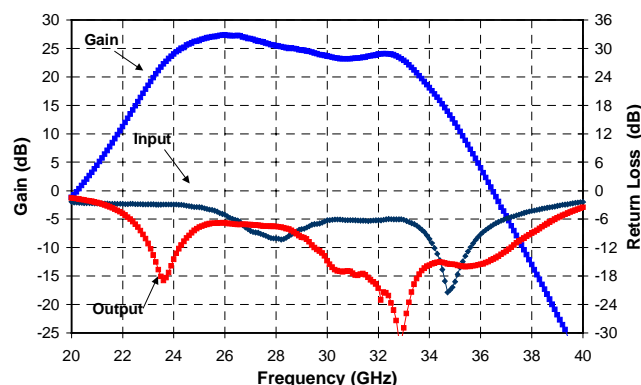
Key Features

- Frequency Range: 24-32 GHz
- 23 dB Nominal Gain
- 35.5 dBm Nominal P1dB @30 GHz
- 36.0 dBm Nominal Psat @30 GHz
- 40 dBc at SCL Pout 20dBm
- 0.25 μ m pHEMT 2MI Technology
- Bias 6 V @ 2.1 A Idq
- Chip size 4.3 x 3.0 x .05 mm

Primary Applications

- Satellite Ground Terminal
- Point-to-Point Radio

Fixtured Data
Bias Conditions: Vd = 6 V, Idq = 2.1A



Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

**TABLE I
MAXIMUM RATINGS**

Symbol	Parameter 1/	Value	Notes
V^+	Positive Supply Voltage	8 V	<u>2/</u>
V^-	Negative Supply Voltage Range	-5V TO 0V	
I^+	Positive Supply Current: Quiescent Under RF Drive	3 A 4 A	<u>2/</u>
$ I_G $	Gate Supply Current	62 mA	
P_{IN}	Input Continuous Wave Power	24 dBm	<u>2/</u>
P_D	Power Dissipation	18.4 W	<u>2/</u> , <u>3/</u>
T_{CH}	Operating Channel Temperature	150 °C	<u>4/</u> , <u>5/</u>
T_M	Mounting Temperature (30 Seconds)	320 °C	
T_{STG}	Storage Temperature	-65 to 150 °C	

- 1/ These ratings represent the maximum operable values for this device.
- 2/ Combinations of supply voltage, supply current, input power, and output power shall not exceed P_D .
- 3/ When operated at this bias condition with a base plate temperature of 70 °C, the median life is 4.6 E+5 hours.
- 4/ Junction operating temperature will directly affect the device median time to failure (T_M). For maximum life, it is recommended that junction temperatures be maintained at the lowest possible levels.
- 5/ These ratings apply to each individual FET.

**TABLE II
DC PROBE TEST
($T_A = 25$ °C, nominal)**

NOTES	SYMBOL	LIMITS		UNITS
		MIN	MAX	
<u>1/</u>	$I_{DSS}(Q35)$	15	70.5	mA
<u>1/</u>	$G_M(Q35)$	33	79.5	mS
<u>1/</u> , <u>2/</u>	$ V_{P(Q1, Q9, Q35)} $	0.5	1.5	V
<u>1/</u> , <u>2/</u>	$ V_{BVGS}(Q35) $	11	30	V
<u>1/</u> , <u>2/</u>	$ V_{BVGD}(Q35) $	11	30	V

- 1/ Q35 is a 150 um Test FET
- 2/ V_P , V_{BVGD} , and V_{BVGS} are negative.

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

TABLE III
RF CHARACTERIZATION TABLE
($T_A = 25^\circ\text{C}$, Nominal)
($V_d = 6\text{V}$, $I_d = 2.1\text{A}$)

SYMBOL	PARAMETER	TEST CONDITION	TYPICAL	UNITS
Gain	Small Signal Gain	$F = 24\text{-}32\text{ GHz}$	23	dB
IRL	Input Return Loss	$F = 24\text{-}32\text{ GHz}$	6	dB
ORL	Output Return Loss	$F = 24\text{-}32\text{ GHz}$	12	dB
PWR	Output Power @ P1dB	$F = 24\text{-}31\text{ GHz}$	35	dBm

Note: Table III Lists the RF Characteristics of typical devices as determined by fixtured measurements.

TABLE IV
THERMAL INFORMATION

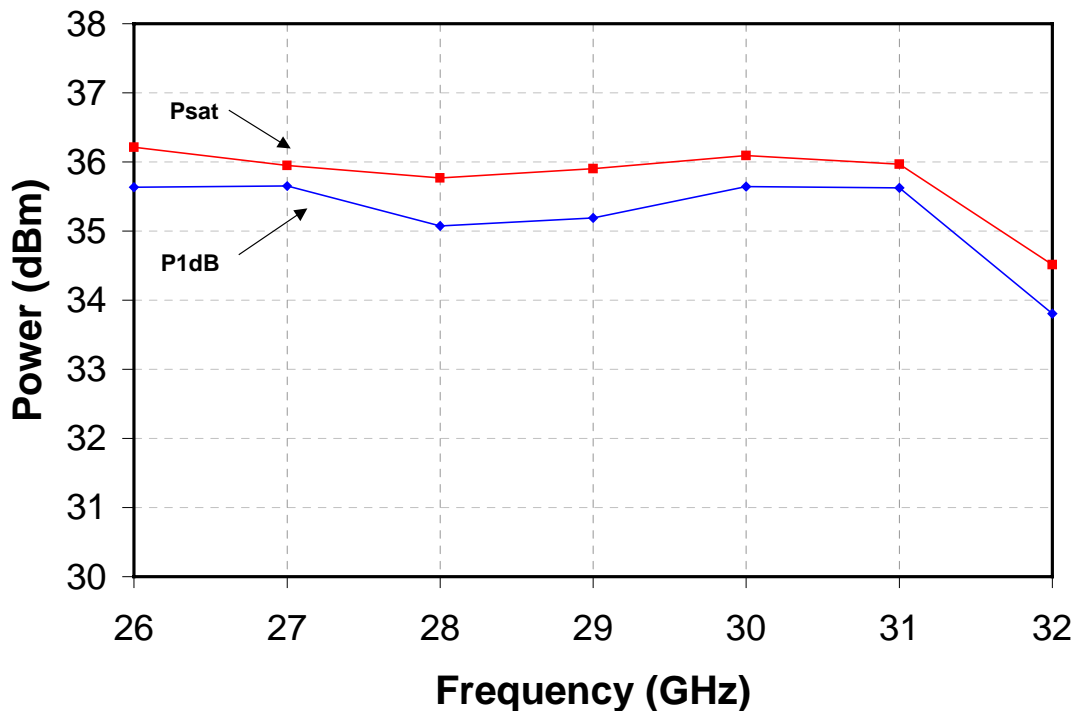
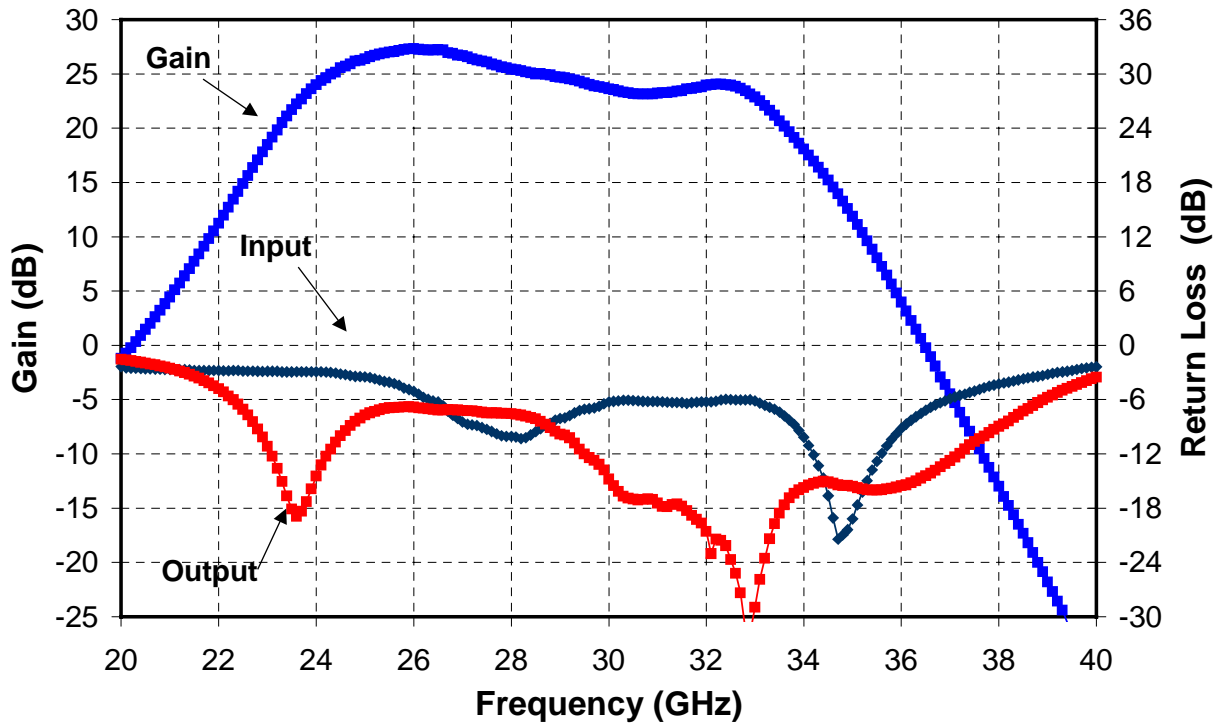
Parameter	Test Conditions	T_{CH} ($^\circ\text{C}$)	$R_{\theta JC}$ ($^\circ\text{C/W}$)	T_M (HRS)
$R_{\theta JC}$ Thermal Resistance (channel to backside of carrier)	$V_d = 6\text{V}$ $I_D = 2.05\text{ A}$ $P_{diss} = 12.3\text{ W}$	128	4.7	7.4E+6

Note: Assumes eutectic attach using 1.5 mil 80/20 AuSn mounted to a 20 mil CuMo Carrier at 70°C baseplate temperature. Worst case condition with no RF applied, 100% of DC power is dissipated.

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

Measured Fixtured Data

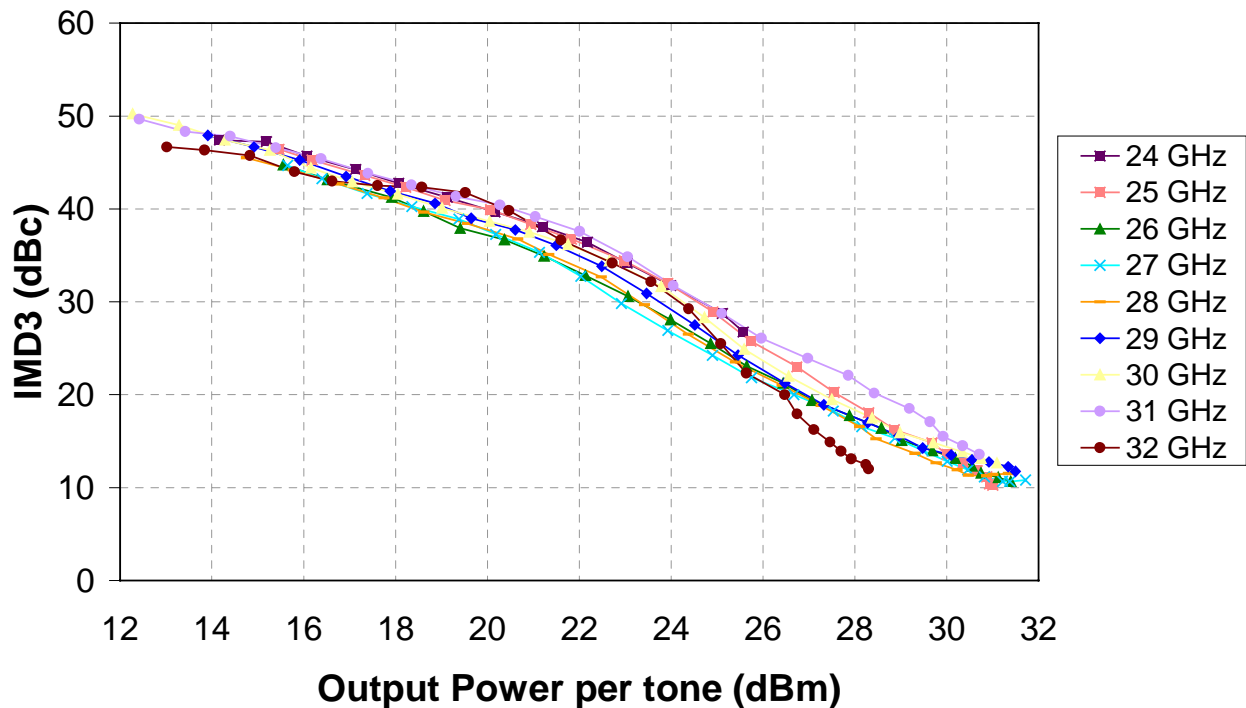
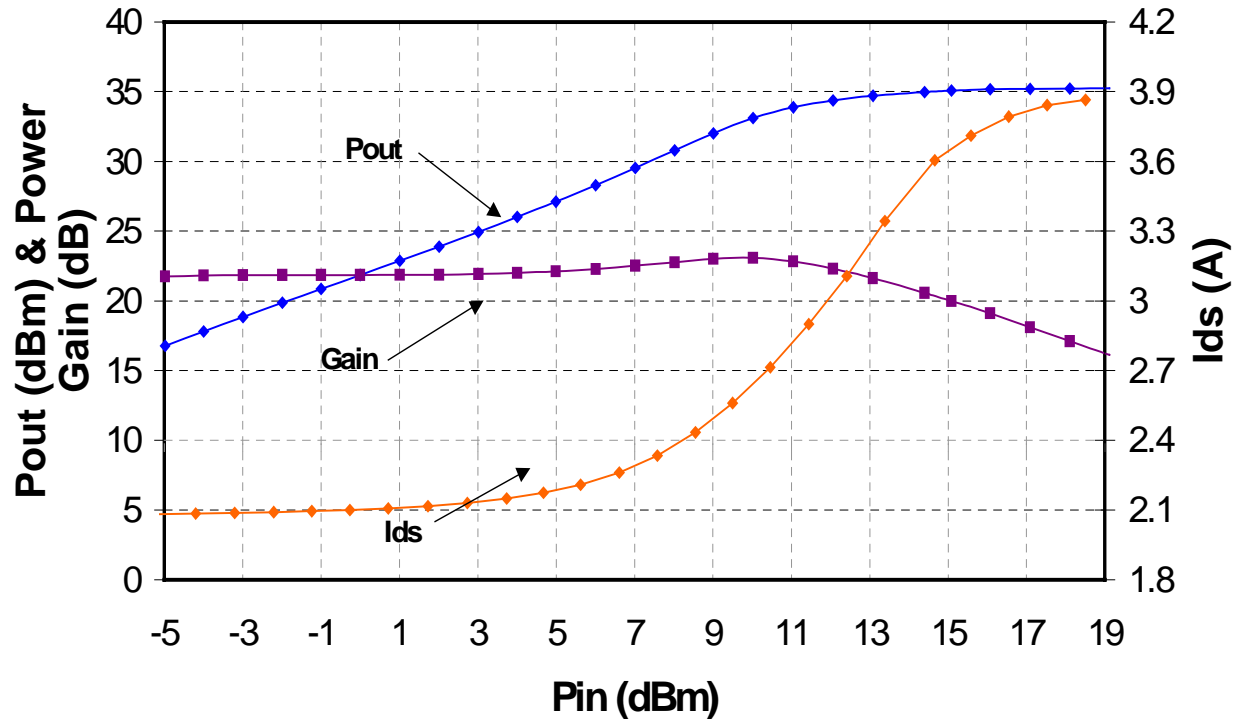
Bias Conditions: $V_d = 6\text{ V}$, $I_d = 2.1\text{ A}$



Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

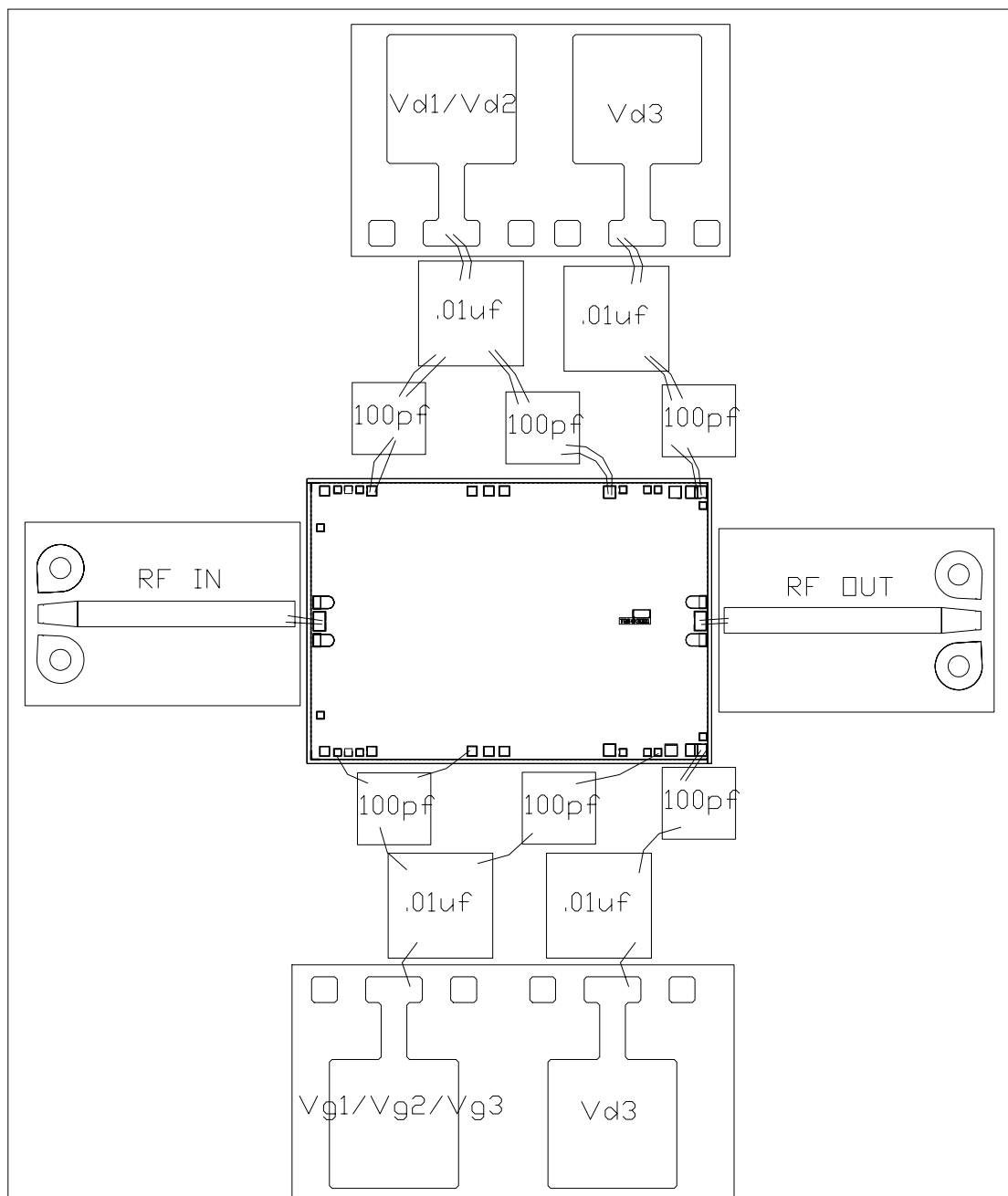
Measured Fixtured Data

Bias Conditions: $V_d = 6\text{ V}$, $I_d = 2.1\text{ A}$



Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

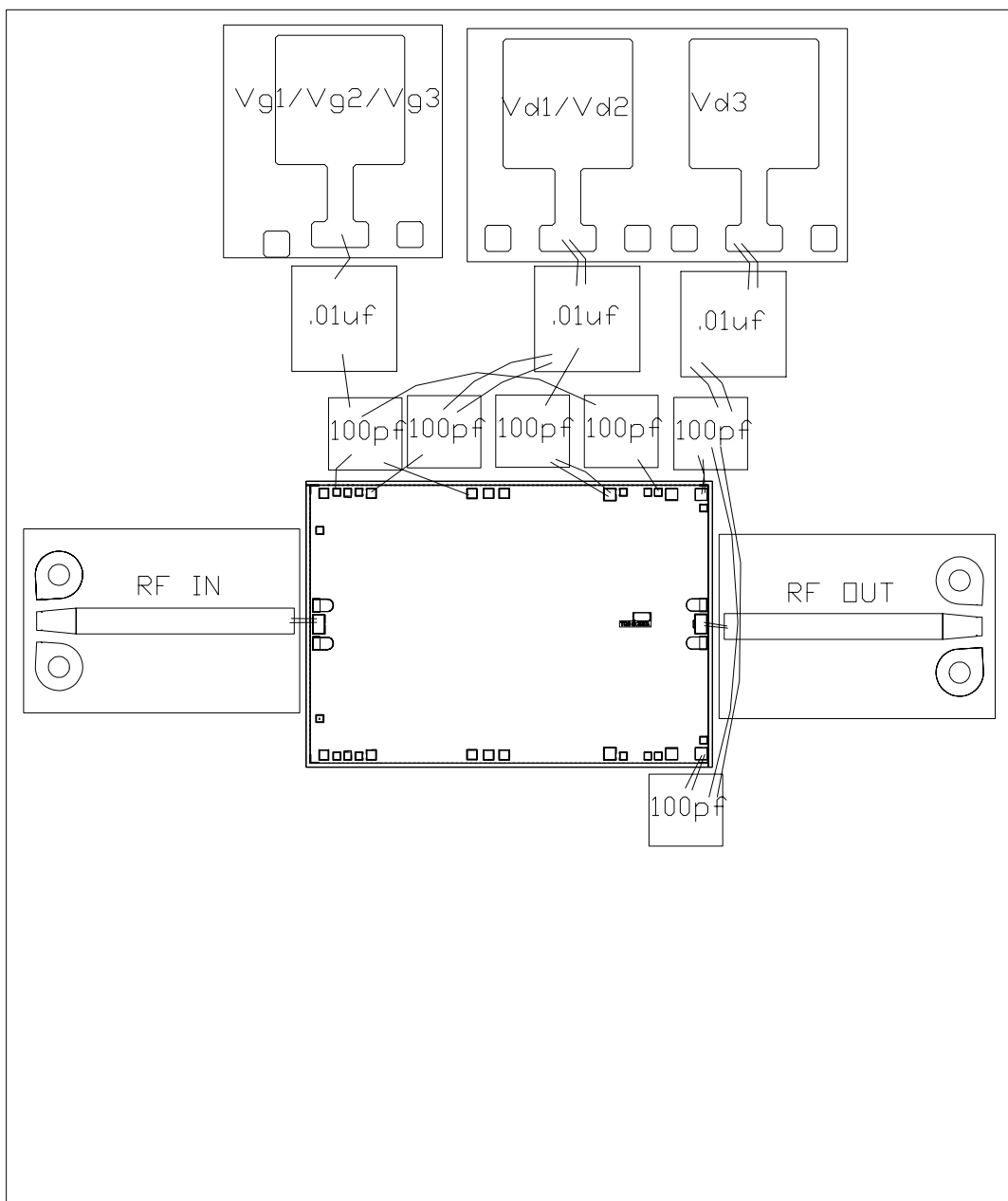
Recommended Chip Assembly & Bonding Diagram Both-Sided Biasing Option



GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

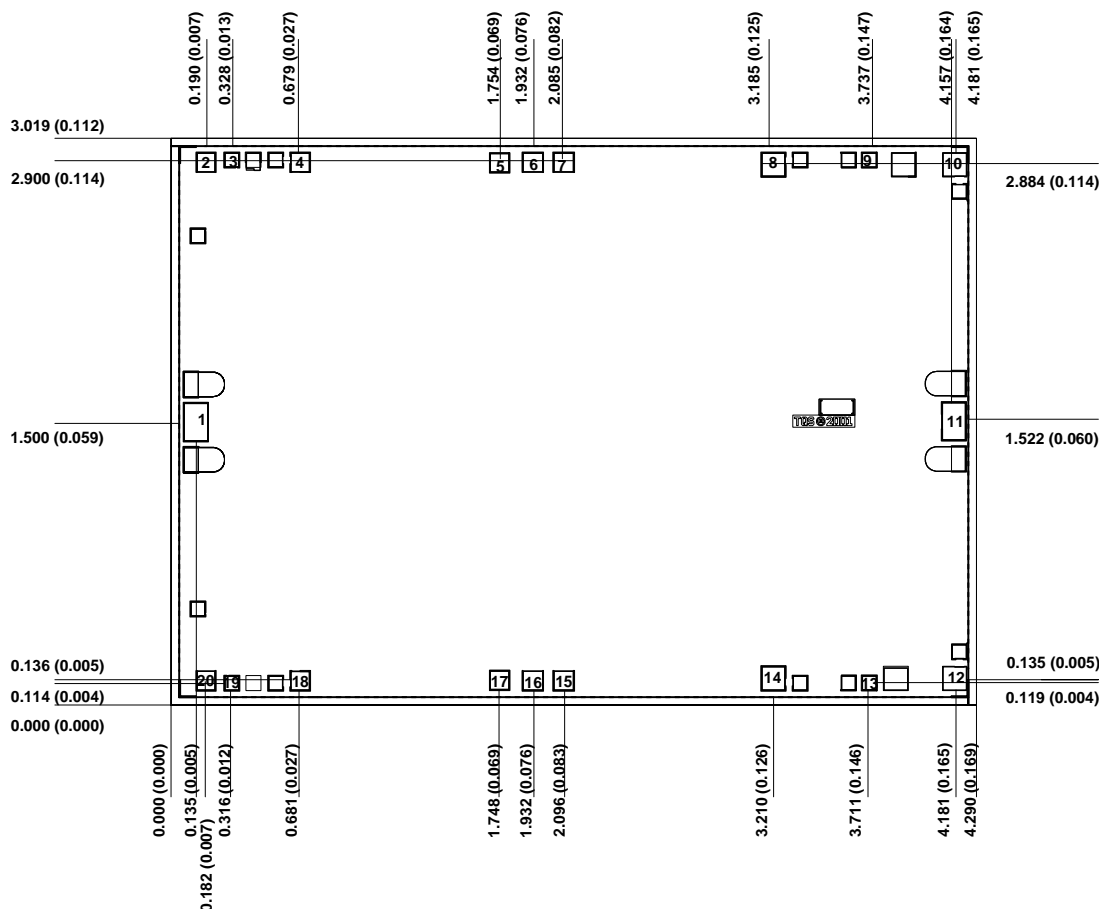
Alternative Chip Assembly & Bonding Diagram Single-Side Biasing Option



GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

Mechanical Drawing



Units: Millimeters (inches)

Thickness: 0.05 (0.002) (reference only)

Chip edge to bond pad dimensions are shown to center of bond pad

Chip size +/- 0.05 (0.002)

GND IS BACKSIDE OF MMIC

Bond pad #1	(RF Input)	0.130 x 0.205 (0.005 x 0.008)
Bond pad #11	(RF Output)	0.130 x 0.205 (0.005 x 0.008)
Bond pad #2, 20	(DC GND)	0.102 x 0.105 (0.004 x 0.004)
Bond pad #3, 19	(VG1)	0.085 x 0.085 (0.003 x 0.003)
Bond pad #4, 18	(VD1)	0.105 x 0.105 (0.004 x 0.004)
Bond pad #5, 17	(VG2)	0.110 x 0.110 (0.004 x 0.004)
Bond pad #6, 7, 15, 16	(DC GND)	0.110 x 0.105 (0.004 x 0.004)
Bond pad #8, 14	(VD2)	0.130 x 0.130 (0.005 x 0.005)
Bond pad #9, 13	(VG3)	0.085 x 0.085 (0.003 x 0.003)
Bond pad #10, 12	(VD3)	0.130 x 0.130 (0.005 x 0.005)

GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

Assembly Process Notes

Reflow process assembly notes:

- Use AuSn (80/20) solder with limited exposure to temperatures at or above 300°C (for 30 sec max).
- An alloy station or conveyor furnace with reducing atmosphere should be used.
- No fluxes should be utilized.
- Coefficient of thermal expansion matching is critical for long-term reliability.
- Devices must be stored in a dry nitrogen atmosphere.

Component placement and adhesive attachment assembly notes:

- Vacuum pencils and/or vacuum collets are the preferred method of pick up.
- Air bridges must be avoided during placement.
- The force impact is critical during auto placement.
- Organic attachment can be used in low-power applications.
- Curing should be done in a convection oven; proper exhaust is a safety concern.
- Microwave or radiant curing should not be used because of differential heating.
- Coefficient of thermal expansion matching is critical.

Interconnect process assembly notes:

- Thermosonic ball bonding is the preferred interconnect technique.
- Force, time, and ultrasonics are critical parameters.
- Aluminum wire should not be used.
- Discrete FET devices with small pad sizes should be bonded with 0.0007-inch wire.
- Maximum stage temperature is 200°C.

GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.